

DESCRIPTION

~~WORKPIECE POLISHING DEVICE~~

TECHNICAL FIELD

[0001]

The present invention relates to a workpiece polishing apparatus.

BACKGROUND ART

[0002]

In production of semiconductor wafers such as silicon wafers, a polishing process to improve surface roughness and flatness of a wafer is one of important processes.

As the precision of devices has recently been increased, there is an increasing need for more precisely flattened semiconductor wafers for use in device fabrication. According to this need, chemical mechanical polishing (CMP) is used as a technique to flatten a surface of semiconductor wafers.

[0003]

Apparatuses for polishing surfaces of a wafer such as a silicon wafer may be classified into two types: a single-side polishing apparatus that polishes one side of a workpiece at a time and a double-side polishing apparatus that polishes both sides simultaneously.

As shown in FIG. 7, for example, a common single-side polishing apparatus is constituted of a turn table 104 to which a polishing pad 107 is attached, a polishing agent supplying mechanism 108, a polishing head 102, and other components. The polishing apparatus 101 of this type holds a workpiece W by the polishing

DESCRIPTION

WORKPIECE POLISHING APPARATUS

TECHNICAL FIELD

[0001]

The present invention relates to a workpiece polishing apparatus.

BACKGROUND ART

[0002]

In production of semiconductor wafers such as silicon wafers, a polishing process to improve surface roughness and flatness of a wafer is one of important processes.

As the precision of devices has recently been increased, there is an increasing need for more precisely flattened semiconductor wafers for use in device fabrication. According to this need, chemical mechanical polishing (CMP) is used as a technique to flatten a surface of semiconductor wafers.

[0003]

Apparatuses for polishing surfaces of a wafer such as a silicon wafer may be classified into two types: a single-side polishing apparatus that polishes one side of a workpiece at a time and a double-side polishing apparatus that polishes both sides simultaneously.

As shown in FIG. 7, for example, a common single-side polishing apparatus is constituted of a turn table 104 to which a polishing pad 107 is attached, a polishing agent supplying mechanism 108, a polishing head 102, and other components. The polishing apparatus 101 of this type holds a workpiece W by the polishing